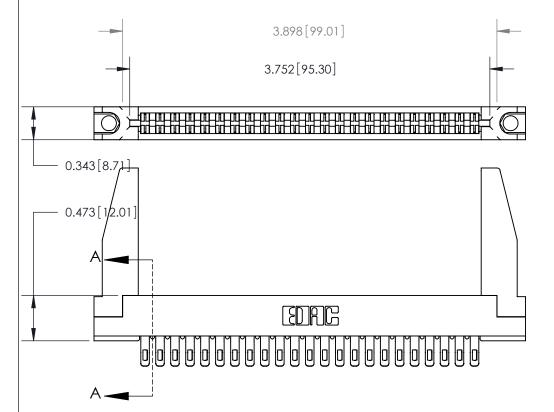
Mounting Option

In-Line Card Guides

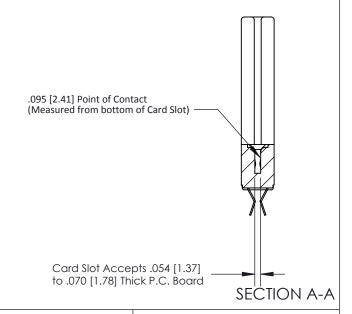
Contact Detail

Extender Board Bend (Code 500 Contacts)

.156 [3.96] Contact Spacing x .200 [5.08] Row Spacing







See Accompanying Pages for:

- **Contact Bend Details**
- **Mounting Options**
- **Features and Specifications**

807 Series High Temp Card Edge Connector Part Number: 807-046-555-278

YOUR CONNECTION TO QUALITY & SERVICE

807 ENG MASTER J.LEE DATE: AUG. 11/09 NTS SHEET 1 OF 4

807 Assembly





ISSUE NUMBE

ORIGINAL



Features

- CSA Approved and UL Recognized
- .156 (3.96) Contact Spacing x .200 (5.08) Row Spacing
- Accepts .062 (1.57) Nominal Thickness P.C. Board
- Low Profile Insulator Body .473 (12.01), with Card Guides
- Contact Termination Options include P.C. Tail, Wire Hole, Wire Wrap, 90 Degree & Extender Board Bends
- Single or Dual Row Configurations
- Large Variety of Mounting Options
- Pre-assembled Card Guides Available
- Accepts Between Contact and In-Contact Polarizing Keys

Specifications

- Insulator Material: DAP
- Contact Material: Copper, Nickel, Tin Alloy CA-725
- Contact Plating: Gold on the Mating Area, Tin on the Contact Tails, Nickel Underplate
- Current Rating: 5 Amperes Continuous
- Contact Resistance: 10 Milliohms Maximum
- Dielectric Withstanding Voltage: 1800 V AC rms at Sea Level Between Adjacent Contacts
- Insulation Resistance: 5000 Megohms Minimum
- Operating Temperature: -65 to +165 °C
- Insertion Force: 16 oz (4.45 N) Maximum per Contact Pair when Tested with a .070 (1.78) Thick Gauge
- Withdrawal Force: 1 oz (0.28 N) Minimum per Contact Pair when Tested with a .054 (1.37) Thick Gauge

807 Series High Temp Card Edge Connector Features and Specifications		ACAD REFERENCE NO. 807 ENG MASTER			
		DRAWN:	J.LEE	DATE: AU	G. 11/09
		CHECKED:		DATE:	
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